

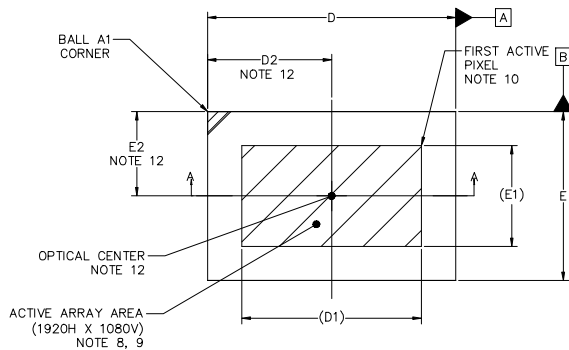
**ODCSP53 5.31x3.61x0.63, 0.5P**  
**CASE 570AA**  
**ISSUE C**

DATE 03 APR 2024

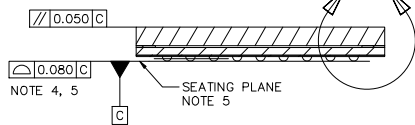
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±0.1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).

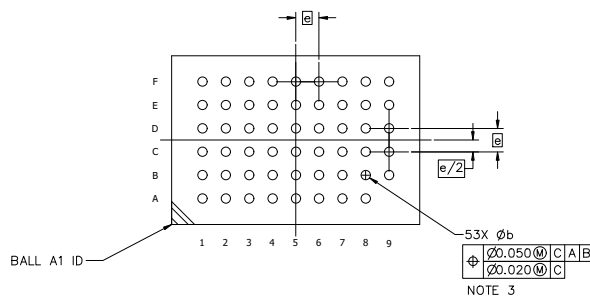
MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.762
A1	0.081	0.101	0.121
A2	0.631 REF		
A3	0.426	0.440	0.454
A4	0.180	0.191	0.202
b	0.184	0.204	0.224
D	5.290	5.315	5.340
D1	3.840 REF		
D2	2.633	2.658	2.683
E	3.590	3.615	3.640
E1	2.160 REF		
E2	1.783	1.808	1.833
e	0.500 BSC		
e/2	0.250 BSC		



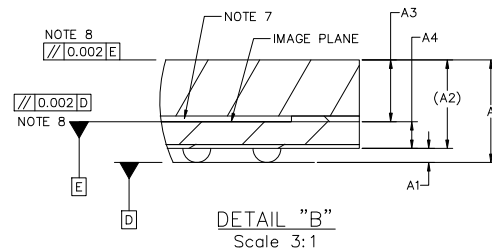
TOP VIEW



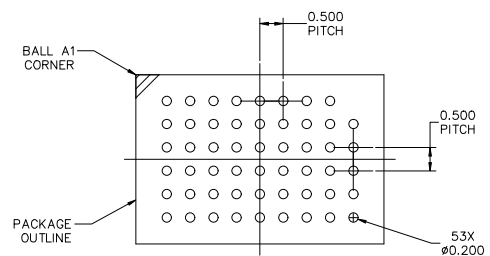
SECTION A-A



BOTTOM VIEW



DETAIL "B"  
Scale 3:1



RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>ODCSP53 5.31x3.61x0.63, 0.5P</b>	<b>PAGE 1 OF 1</b>

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